

8A, 50V - 1000V Standard Bridge Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for printed circuit board
- High case dielectric strength
- Typical I_R less than 0.1µA
- High surge current capability
- UL Recognized File # E-326243
- RoHS Compliant

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- Switching mode power supply (SMPS)
- Adapters
- Lighting application

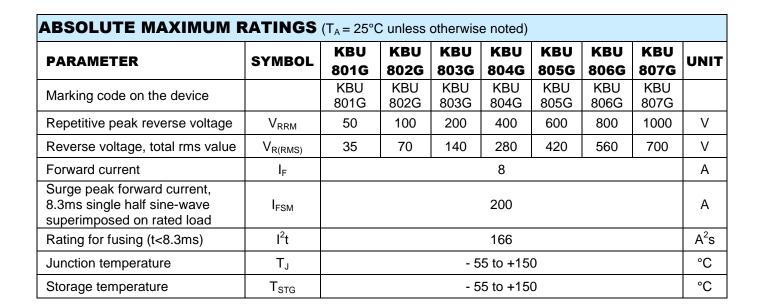
MECHANICAL DATA

- Case: KBU
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Mounting torque: 0.56 N⋅m maximum
- Polarity: As marked
- Weight: 7.20g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I _F	8	Α			
V_{RRM}	50 - 1000	V			
I _{FSM}	200	Α			
T_{JMAX}	150	°C			
Package	KBU				
Configuration	Quad				







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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	18	°C/W		
Junction-to-case thermal resistance	R _{eJC}	3	°C/W		

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode ⁽¹⁾	I _F = 4A, T _J = 25°C	V _F	-	1.0	V
Forward voltage per diode	I _F = 8A, T _J = 25°C		-	1.1	V
Reverse current @ rated V _R per diode ⁽²⁾	T _J = 25°C	_	-	5	μΑ
Reverse current @ rated v _R per diode.	T _J = 125°C	l _R	-	500	μΑ
Junction capacitance per diode	$1MHz$, $V_R = 4.0V$	CJ	400	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING			
KBU8xG	KBU	100 / Tray			

Notes:

1. "x" defines voltage from 50V(KBU801G) to 1000V(KBU807G)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

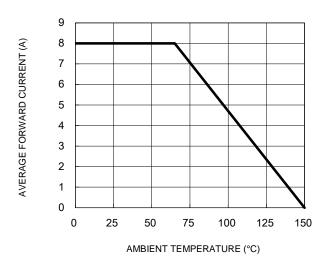


Fig.3 Typical Reverse Characteristics

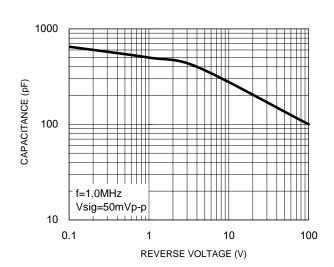
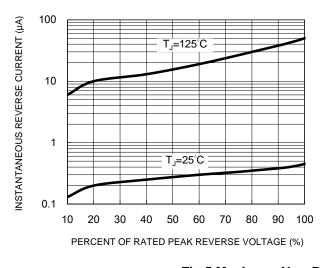


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



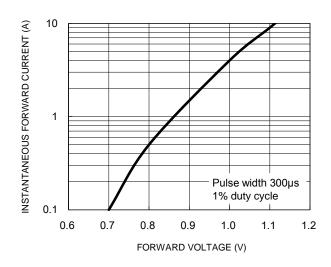
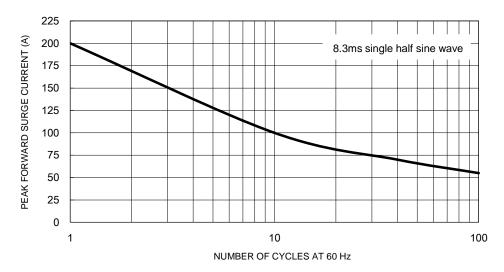


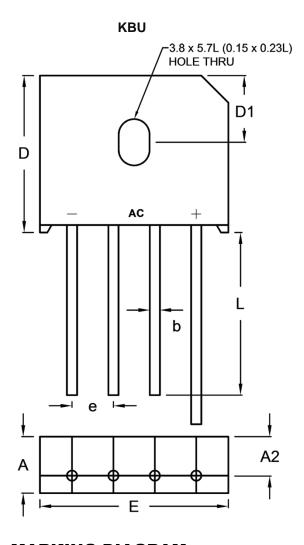
Fig.5 Maximum Non-Repetitive Forward Surge Current







PACKAGE OUTLINE DIMENSIONS



DIM.	Unit (mm)		Unit (inch)		
DIIVI.	Min.	Max.	Min.	Max.	
Α	6.8	7.1	0.268	0.280	
A2	4.6	5.0	0.181	0.197	
b	1.2	1.3	0.047	0.051	
D	18.8	19.8	0.740	0.780	
D1	8.2 (TYP)		0.322 (TYP)		
E	22.7	23.7	0.894	0.933	
е	4.6	5.6	0.181	0.220	
L	20.0	-	0.787	-	

MARKING DIAGRAM



P/N = Marking Code YWW = Date Code F = Factory Code



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